

ABSTRACT

The present invention relates to a Cu-Sn-O alloy plating having an oxygen content of 0.3 to 50 at%, a copper content of 20 to 80 at%, and a tin content of 10 to 70 at% in the plating. The present invention provides a copper tin alloy plating that has excellent plating adhesion and disengaging force stability and particularly a Cu-Sn-O alloy plating that has a blackish color tone without containing any controlled substances.